



银钯铂导体浆料

9562

CERMET PLATINUM PALLADIUM SILVER CONDUCTOR

ESL9562是低成本的引线键合银钯铂浆料。具有优良的可焊性，附着力强，良好的老化键合保持性能。该产品能作为烧结温度为850°C的一系列电阻浆料的端头导体浆料使用。

ESL 9562 is a low cost wire bondable PtPdAg. It exhibits excellent solderability and adhesion with good aged bond retention. ESL 9562 can be used as a termination for 850°C fired resistor series.

浆料数据 PASTE DATA

流变学 RHEOLOGY:	Thixotropic, screen-printable paste	触变性, 丝网印刷浆料
粘度 VISCOSITY: (Brookfield RVT, ABZ Spindle, 10 rpm, 25.5°C± 0.5°C)		185±15 帕·秒
保质期 SHELF LIFE(25°C):		6个月

操作工艺 PROCESSING

丝网目数/乳胶厚度 SCREEN MESH/EMULSION:		325目/25 微米
流平时间 LEVELING TIME(25°C):		5-10 分钟
干燥时间 DRYING(125°C):		10-15 分钟
烧结温度范围 FIRING TEMPERATURE RANGE:		850°C-930°C
最佳温度 OPTIMUM:		930°C
峰值时间 TIME AT PEAK:		10-12 分钟
升温/降温速率 RATE OF ASCENT/DESCENT:		60°C-100°C/分钟
标准基板 SUBSTRATE OF CALIBRATION:		96% 氧化铝
稀释剂 THINNER:		ESL 401

产品特性 TYPICAL PROPERTIES

烧结膜厚 FIRED THICKNESS:		12.5±2.5 微米
覆盖率 COVERAGE:		90-100 cm ² /g
方阻 RESISTIVITY:		6 mΩ/□
图形解析度 PRINTING RESOLUTION: (Line/Space)		250 μm x 250 μm
焊料浸润性 SOLDER WETTABILITY:(RMA flux,5sec. Dip)	(62 Sn/36 Pb/2 Ag, 220°C±5°C)	very good
	(63 Sn/37 Pb, 250°C±5°C)	good

抗焊料侵蚀性 SOLDER LEACH:

(No. of 10 sec. dips to double resistance of 0.25 mm

wide x 100 mm long conductor, 62 Sn/36 Pb/2 Ag, 220°C±5°C)

6-12 dips

附着力 ADHESION:(90° pull, 2.0 mm x 2.0 mm pads, 62 Sn/36 Pb/2 Ag)

初始附着力 Initial pull strength: > 44 N

老化附着力 Aged 48 hours at 150°C: 26-44 N

超声波引线键合 ULTRASONIC WIRE BOND:(25 μm Al wire)

8-10 grams

热超声引线键合 THERMOSONIC WIRE BOND:(25 μm Au wire)

5-8 grams

抗迁移性 MIGRATION RESISTANCE:Excellent when protected with ESL 4904 or similar overglaze

fair to poor

兼容的ESL浆料 COMPATIBILITY:

ESL4905-C、ESL 3900 Series、ESL 3701